

### **AMENDMENTS TO THE CLAIMS**

This listing of claims replaces all prior versions of claims in the application.

1. (Previously presented): A method for forming a multilayer circuit structure, which comprises steps of:

forming a curable composition film that contains an insulating polymer and a curing agent, as the outermost layer of an inner layer board; then

bringing a compound that has a structure capable of coordinating to a metal, into contact with the surface of the curable composition film; then

curing the curable composition film to form an electrical insulating layer; then

hydrophilicating the surface of the resulting electrical insulating layer; then

forming a metal thin-film layer of an ethylenediaminetetraacetate-copper complex on the surface of the electrical insulating layer; and then

forming a conductor circuit layer that contains the metal thin-film layer.

2. (Original): The method for forming a multilayer circuit structure as claimed in claim 1, wherein the hydrophilicating treatment step is a step of bringing the electrical insulating layer into contact with a mixture solution that comprises from 65 g/liter to 150 g/liter of potassium permanganate and from 0.75 normalities to 1.5 normalities of an alkali hydroxide, for surface-treatment of the electrical insulating layer.

3. (Original): The method for forming a multilayer circuit structure as claimed in claim 1, wherein the curable composition film that contains an insulating polymer and a curing agent and is formed as the outermost layer of the inner layer board is formed according to any of a method of laminating any of a shaped film or sheet of a curable composition that contains an insulating polymer and a curing agent, on the inner layer board, or a method of by applying a varnish prepared by dissolving a curable composition containing an insulating polymer and a curing agent in a solvent, onto the surface of the inner layer board and drying it thereon.

4. (Original): The method for forming a multilayer circuit structure as claimed in claim 1, which includes a step of heating the inner layer board with the conductor circuit layer formed thereon, after the step of forming the conductor circuit layer.

5. (Cancelled).